

**Topical Workshop on Electronics
for Particle Physics
TWEPP 2024**

Oral Presentation Award

**Development of a novel low-mass
module flex PCB using nano-wire-
based flip-chip interconnection**

Presenter: Julian Weick¹

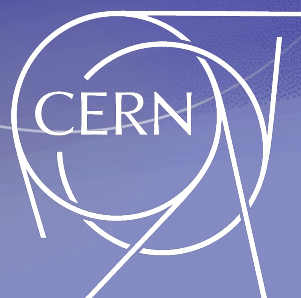
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